

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): An ultrasonic probe, comprising[[:]]; a piezoelectric transducer for sending and receiving an ultrasonic wave[[:]]; and a conductive substrate for applying current to the piezoelectric transducer, wherein the conductive substrate is arranged oppositely to a side face of the piezoelectric transducer and has an end portion that is closer to the piezoelectric transducer and that is arranged outside of the side face of the piezoelectric transducer, and a conductive material is arranged in a corner portion formed by the piezoelectric transducer and the conductive substrate, the conductive material electrically connecting the piezoelectric transducer to the conductive substrate.

Claim 2 (Original): The ultrasonic probe according to claim 1, wherein the conductive substrate has a signal wiring and an earth wiring.

Claim 3 (Original): The ultrasonic probe according to claim 2, wherein a nonconductive material insulates a jointed portion of the piezoelectric transducer with the signal wiring from a jointed portion of the piezoelectric transducer with the earth wiring.

Claim 4 (Currently Amended): The ultrasonic probe according to claim 1, wherein the conductive substrate has [[the]] a signal wiring and [[the]] an earth wiring, either one of the wirings is electrically connected to a first electrode formed on a surface side of the piezoelectric transducer by the conductive material arranged in a first

corner portion formed by a surface of the piezoelectric transducer and the conductive substrate, and

the other wiring is electrically connected to a second electrode formed on a back side of the piezoelectric transducer by the conductive material arranged in a second corner portion formed by the back of the piezoelectric transducer and the conductive substrate.

Claim 5 (Original): The ultrasonic probe according to claim 1,
wherein the conductive material supplied to the corner portion is coated by a nonconductive material.

Claim 6 (Original): The ultrasonic probe according to claim 1,
wherein a face of the conductive substrate at a side of the piezoelectric transducer is disposed on a plane equal to a side face of the piezoelectric transducer or a plane spaced from the piezoelectric transducer.

Claim 7 (Original): The ultrasonic probe according to claim 1, wherein the conductive substrate is formed flat in the vicinity of the piezoelectric transducer.

Claim 8 (Original): The ultrasonic probe according to claim 1, wherein the conductive material is formed in a fillet pattern.

Claim 9 (Currently Amended): ~~[[An]]~~ The ultrasonic probe comprising; according to claim 1, wherein the conductive substrate comprises:

~~a piezoelectric transducer for sending and receiving an ultrasonic wave;~~

a first conductive substrate having a signal wiring for applying current to the piezoelectric transducer[[,]]; and

a second conductive substrate having an earth wiring for connecting to the piezoelectric transducer,

wherein the first conductive substrate is arranged oppositely to a first side face of the piezoelectric transducer,

the second conductive substrate is arranged oppositely to a second side face of the piezoelectric transducer,

the earth wiring is electrically connected to a first electrode formed on a first main-face side of the piezoelectric transducer by a conductive material arranged in a first corner portion formed by the first conductive substrate,

and the signal wiring is electrically connected to a second electrode formed on a second main-face side of the piezoelectric transducer by a conductive material arranged in a second corner portion formed by the second conductive substrate.

Claim 10 (Original): The ultrasonic probe according to claim 9,

wherein a nonconductive material insulates a jointed portion of the piezoelectric transducer with the signal wiring from a jointed portion of the piezoelectric transducer with the earth wiring.

Claim 11 (Original): The ultrasonic probe according to claim 9, wherein the conductive material is coated by a nonconductive material.

Claim 12 (Original): The ultrasonic probe according to claim 9,
wherein a face of the conductive substrate at a side of the piezoelectric transducer is
disposed on a plane equal to a side face of the piezoelectric transducer or a plane spaced from
the piezoelectric transducer.

Claim 13 (Original): The ultrasonic probe according to claim 9, wherein the
conductive material is formed in a fillet pattern.

Claim 14 (Withdrawn): In a fabrication method of an ultrasonic probe for fabricating
the ultrasonic probe having a piezoelectric transducer for sending and receiving an ultrasonic
wave, and a conductive substrate for applying current to the piezoelectric transducer, the
method comprising;

a disposing process for disposing the conductive substrate oppositely to a side face of
the piezoelectric transducer,

a supplying process of a conductive material for supplying the conductive material to
a corner portion formed by the piezoelectric transducer and the conductive substrate,

and a heating process for electrically connecting the piezoelectric transducer to the
conductive substrate by heating the conductive material.

Claim 15 (Withdrawn): The method for fabricating the ultrasonic probe according to
claim 14,

wherein a soldering material is used as the conductive material, and a contact type
heating unit is used in heating the soldering material.

Claim 16 (Withdrawn): The method for fabricating the ultrasonic probe according to claim 14, wherein the soldering material is used as the conductive material, and a non-contact-type heating unit is used in heating the soldering material.

Claim 17 (Withdrawn): The method for fabricating the ultrasonic probe according to claim 14, wherein a thermosetting material is used as the conductive material.

Claim 18 (Withdrawn): The method for fabricating the ultrasonic probe according to claim 14, wherein a soldering cream is used as the conductive material.

Claim 19 (Withdrawn): The method for fabricating the ultrasonic probe according to claim 14, wherein a photo-reactive hardening material is used as the conductive material.

Claim 20 (Withdrawn): The method for fabricating the ultrasonic probe according to claim 14, wherein after the piezoelectric transducer is electrically connected to the conductive substrate, the piezoelectric transducer is repolarized.

Claim 21 (New): The ultrasonic probe of claim 1, wherein the conductive substrate is flat-shaped on the side face of the piezoelectric transducer.